

Welcome to [E-XFL.COM](#)

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	147456
Number of I/O	177
Number of Gates	1000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a3p1000-1fgg256i

I/Os Per Package¹

ProASIC3 Devices	A3P015 ²	A3P030	A3P060	A3P125	A3P250 ³	A3P400 ³	A3P600	A3P1000		
Cortex-M1 Devices					M1A3P250 ^{3,5}	M1A3P400 ³	M1A3P600	M1A3P1000		
Package	I/O Type									
	Single-Ended I/O	Single-Ended I/O	Single-Ended I/O	Single-Ended I/O	Single-Ended I/O ⁴	Differential I/O Pairs	Single-Ended I/O ⁴	Differential I/O Pairs	Single-Ended I/O ⁴	Differential I/O Pairs
QN48	–	34	–	–	–	–	–	–	–	–
QN68	49	49	–	–	–	–	–	–	–	–
QN132 ⁷	–	81	80	84	87	19	–	–	–	–
CS121	–	–	96	–	–	–	–	–	–	–
VQ100	–	77	71	71	68	13	–	–	–	–
TQ144	–	–	91	100	–	–	–	–	–	–
PQ208	–	–	–	133	151	34	151	34	154	35
FG144	–	–	96	97	97	24	97	25	97	25
FG256 ^{5,6}	–	–	–	–	157	38	178	38	177	43
FG484 ⁶	–	–	–	–	–	–	194	38	235	60
										74

Notes:

- When considering migrating your design to a lower- or higher-density device, refer to the [ProASIC3 FPGA Fabric User Guide](#) to ensure complying with design and board migration requirements.
- A3P015 is not recommended for new designs.
- For A3P250 and A3P400 devices, the maximum number of LVPECL pairs in east and west banks cannot exceed 15. Refer to the [ProASIC3 FPGA Users Guide](#) for position assignments of the 15 LVPECL pairs.
- Each used differential I/O pair reduces the number of single-ended I/Os available by two.
- The M1A3P250 device does not support FG256 package.
- FG256 and FG484 are footprint-compatible packages.
- Package not available.

Table 1 • ProASIC3 FPGAs Package Sizes Dimensions

Package	CS121	QN48	QN68	QN132 [*]	VQ100	TQ144	PQ208	FG144	FG256	FG484
Length × Width (mm × mm)	6 × 6	6 × 6	8 × 8	8 × 8	14 × 14	20 × 20	28 × 28	13 × 13	17 × 17	23 × 23
Nominal Area (mm ²)	36	36	64	64	196	400	784	169	289	529
Pitch (mm)	0.5	0.4	0.4	0.5	0.5	0.5	0.5	1.0	1.0	1.0
Height (mm)	0.99	0.90	0.90	0.75	1.00	1.40	3.40	1.45	1.60	2.23

Note: * Package not available

2 – ProASIC3 DC and Switching Characteristics

General Specifications

Operating Conditions

Stresses beyond those listed in [Table 2-1](#) may cause permanent damage to the device.

Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Absolute Maximum Ratings are stress ratings only; functional operation of the device at these or any other conditions beyond those listed under the Recommended Operating Conditions specified in [Table 2-2](#) on page 2-2 is not implied.

Table 2-1 • Absolute Maximum Ratings

Symbol	Parameter	Limits	Units
VCC	DC core supply voltage	–0.3 to 1.65	V
VJTAG	JTAG DC voltage	–0.3 to 3.75	V
VPUMP	Programming voltage	–0.3 to 3.75	V
VCCPLL	Analog power supply (PLL)	–0.3 to 1.65	V
VCCI	DC I/O output buffer supply voltage	–0.3 to 3.75	V
VMV	DC I/O input buffer supply voltage	–0.3 to 3.75	V
VI	I/O input voltage	–0.3 V to 3.6 V (when I/O hot insertion mode is enabled) –0.3 V to (VCCI + 1 V) or 3.6 V, whichever voltage is lower (when I/O hot-insertion mode is disabled)	V
T _{STG} ²	Storage temperature	–65 to +150	°C
T _J ²	Junction temperature	+125	°C

Notes:

1. The device should be operated within the limits specified by the datasheet. During transitions, the input signal may undershoot or overshoot according to the limits shown in [Table 2-4](#) on page 2-3.
2. VMV pins must be connected to the corresponding VCCI pins. See the "VMVx I/O Supply Voltage (quiet)" section on [page 3-1](#) for further information.
3. For flash programming and retention maximum limits, refer to [Table 2-3](#) on page 2-3, and for recommended operating limits, refer to [Table 2-2](#) on page 2-2.

Table 2-11 • Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings¹
Applicable to Advanced I/O Banks

	C _{LOAD} (pF)	VCCI (V)	Static Power PDC3 (mW) ²	Dynamic Power PAC10 (μW/MHz) ³
Single-Ended				
3.3 V LVTTL / 3.3 V LVC MOS	35	3.3	–	468.67
3.3 V LVC MOS Wide Range ⁴	35	3.3	–	468.67
2.5 V LVC MOS	35	2.5	–	267.48
1.8 V LVC MOS	35	1.8	–	149.46
1.5 V LVC MOS (JESD8-11)	35	1.5	–	103.12
3.3 V PCI	10	3.3	–	201.02
3.3 V PCI-X	10	3.3	–	201.02
Differential				
LVDS	–	2.5	7.74	88.92
LVPECL	–	3.3	19.54	166.52

Notes:

1. Dynamic power consumption is given for standard load and software default drive strength and output slew.
2. PDC3 is the static power (where applicable) measured on VCCI.
3. PAC10 is the total dynamic power measured on VCC and VCCI.
4. All LVC MOS 3.3 V software macros support LVC MOS 3.3 V wide range as specified in the JESD8-B specification.

Table 2-12 • Summary of I/O Output Buffer Power (Per Pin) – Default I/O Software Settings¹
Applicable to Standard Plus I/O Banks

	C _{LOAD} (pF)	VCCI (V)	Static Power PDC3 (mW) ²	Dynamic Power PAC10 (μW/MHz) ³
Single-Ended				
3.3 V LVTTL / 3.3 V LVC MOS	35	3.3	–	452.67
3.3 V LVC MOS Wide Range ⁴	35	3.3	–	452.67
2.5 V LVC MOS	35	2.5	–	258.32
1.8 V LVC MOS	35	1.8	–	133.59
1.5 V LVC MOS (JESD8-11)	35	1.5	–	92.84
3.3 V PCI	10	3.3	–	184.92
3.3 V PCI-X	10	3.3	–	184.92

Notes:

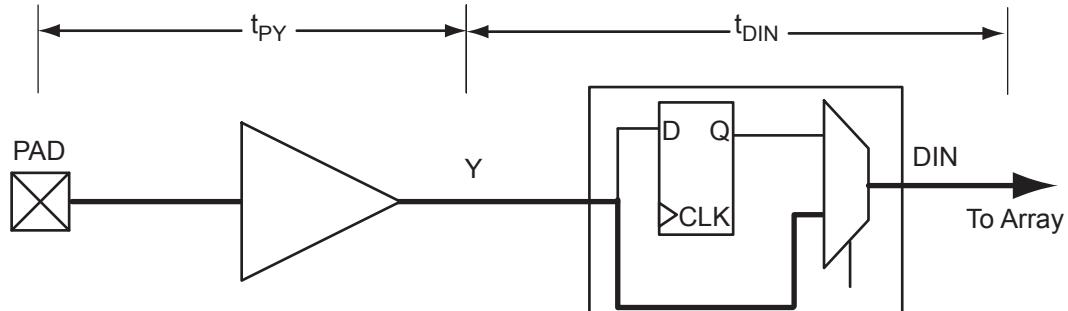
1. Dynamic power consumption is given for standard load and software default drive strength and output slew.
2. PDC3 is the static power (where applicable) measured on VMV.
3. PAC10 is the total dynamic power measured on VCC and VMV.
4. All LVC MOS 3.3 V software macros support LVC MOS 3.3 V wide range as specified in the JESD8-B specification.

Table 2-13 • Summary of I/O Output Buffer Power (Per Pin) – Default I/O Software Settings¹
Applicable to Standard I/O Banks

	C _{LOAD} (pF)	VCCI (V)	Static Power PDC3 (mW) ²	Dynamic Power PAC10 (μW/MHz) ³
Single-Ended				
3.3 V LVTTL / 3.3 V LVCMOS	35	3.3	–	431.08
3.3 V LVCMOS Wide Range ⁴	35	3.3	–	431.08
2.5 V LVCMOS	35	2.5	–	247.36
1.8 V LVCMOS	35	1.8	–	128.46
1.5 V LVCMOS (JESD8-11)	35	1.5	–	89.46

Notes:

1. Dynamic power consumption is given for standard load and software default drive strength and output slew.
2. P_{DC3} is the static power (where applicable) measured on VCCI.
3. P_{AC10} is the total dynamic power measured on VCC and VCCI.
4. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD8-B specification.



$$t_{PY} = \text{MAX}(t_{PY}(R), t_{PY}(F))$$

$$t_{DIN} = \text{MAX}(t_{DIN}(R), t_{DIN}(F))$$

I/O Interface

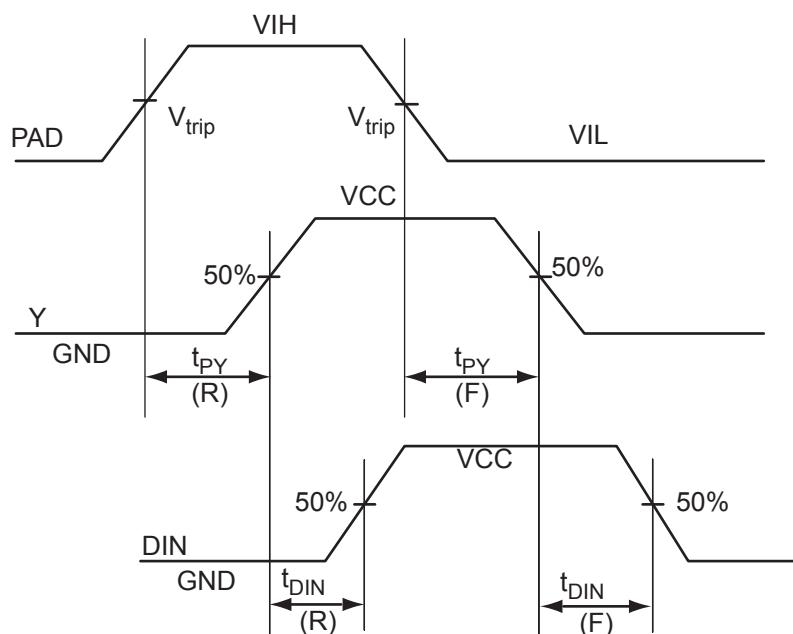


Figure 2-4 • Input Buffer Timing Model and Delays (Example)

Table 2-25 • Summary of I/O Timing Characteristics—Software Default Settings

–2 Speed Grade, Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst Case VCC = 1.425 V,
 Worst-Case VCCI (per standard)
 Standard Plus I/O Banks

I/O Standard	Drive Strength	Equiv. Software Default Drive Strength Option ¹	Slew Rate	Capacitive Load (pF)	External Resistor	t _{DOUT} (ns)	t _{DP} (ns)	t _{DIN} (ns)	t _{PR} (ns)	t _{EOUT} (ns)	t _{ZL} (ns)	t _{ZH} (ns)	t _{LZ} (ns)	t _{HZ} (ns)	t _{ZLs} (ns)	t _{ZHs} (ns)	Units
3.3 V LVTTL / 3.3 V LVCMOS	12 mA	12 mA	High	35	–	0.45	2.36	0.03	0.75	0.32	2.40	1.93	2.08	2.41	4.07	3.60	ns
3.3 V LVCMOS Wide Range ²	100 µA	12 mA	High	35	–	0.45	3.65	0.03	1.14	0.32	3.65	2.93	3.22	3.72	6.18	5.46	ns
2.5 V LVCMOS	12 mA	12 mA	High	35	–	0.45	2.39	0.03	0.97	0.32	2.44	2.35	2.11	2.32	4.11	4.02	ns
1.8 V LVCMOS	8 mA	8 mA	High	35	–	0.45	3.03	0.03	0.90	0.32	2.87	3.03	2.19	2.32	4.54	4.70	ns
1.5 V LVCMOS	4 mA	4 mA	High	35	–	0.45	3.61	0.03	1.06	0.32	3.35	3.61	2.26	2.34	5.02	5.28	ns
3.3 V PCI	Per PCI spec	–	High	10	25 ⁴	0.45	1.72	0.03	0.64	0.32	1.76	1.27	2.08	2.41	3.42	2.94	ns
3.3 V PCI-X	Per PCI-X spec	–	High	10	25 ⁴	0.45	1.72	0.03	0.62	0.32	1.76	1.27	2.08	2.41	3.42	2.94	ns

Notes:

1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ±100 µA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
2. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD8-B specification.
3. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.
4. Resistance is used to measure I/O propagation delays as defined in PCI specifications. See [Figure 2-11 on page 2-64](#) for connectivity. This resistor is not required during normal operation.

Table 2-55 • 3.3 V LVTTL / 3.3 V LVCMOS Low Slew

 Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V
 Applicable to Standard I/O Banks

Drive Strength	Equiv. Software Default Drive Strength Option ¹	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	Units
100 μA	2 mA	Std.	0.60	14.64	0.04	1.52	0.43	14.64	12.97	3.21	3.15	ns
		-1	0.51	12.45	0.04	1.29	0.36	12.45	11.04	2.73	2.68	ns
		-2	0.45	10.93	0.03	1.13	0.32	10.93	9.69	2.39	2.35	ns
100 μA	4 mA	Std.	0.60	14.64	0.04	1.52	0.43	14.64	12.97	3.21	3.15	ns
		-1	0.51	12.45	0.04	1.29	0.36	12.45	11.04	2.73	2.68	ns
		-2	0.45	10.93	0.03	1.13	0.32	10.93	9.69	2.39	2.35	ns
100 μA	6 mA	Std.	0.60	10.16	0.04	1.52	0.43	10.16	9.08	3.71	3.98	ns
		-1	0.51	8.64	0.04	1.29	0.36	8.64	7.73	3.15	3.39	ns
		-2	0.45	7.58	0.03	1.13	0.32	7.58	6.78	2.77	2.97	ns
100 μA	8 mA	Std.	0.60	10.16	0.04	1.52	0.43	10.16	9.08	3.71	3.98	ns
		-1	0.51	8.64	0.04	1.29	0.36	8.64	7.73	3.15	3.39	ns
		-2	0.45	7.58	0.03	1.13	0.32	7.58	6.78	2.77	2.97	ns

Notes:

1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is $\pm 100 \mu\text{A}$. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

Timing Characteristics

Table 2-70 • 1.8 V LVC MOS High Slew

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.7 V
 Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.66	11.86	0.04	1.22	0.43	9.14	11.86	2.77	1.66	11.37	14.10	ns
	-1	0.56	10.09	0.04	1.04	0.36	7.77	10.09	2.36	1.41	9.67	11.99	ns
	-2	0.49	8.86	0.03	0.91	0.32	6.82	8.86	2.07	1.24	8.49	10.53	ns
4 mA	Std.	0.66	6.91	0.04	1.22	0.43	5.86	6.91	3.22	2.84	8.10	9.15	ns
	-1	0.56	5.88	0.04	1.04	0.36	4.99	5.88	2.74	2.41	6.89	7.78	ns
	-2	0.49	5.16	0.03	0.91	0.32	4.38	5.16	2.41	2.12	6.05	6.83	ns
6 mA	Std.	0.66	4.45	0.04	1.22	0.43	4.18	4.45	3.53	3.38	6.42	6.68	ns
	-1	0.56	3.78	0.04	1.04	0.36	3.56	3.78	3.00	2.88	5.46	5.69	ns
	-2	0.49	3.32	0.03	0.91	0.32	3.12	3.32	2.64	2.53	4.79	4.99	ns
8 mA	Std.	0.66	3.92	0.04	1.22	0.43	3.93	3.92	3.60	3.52	6.16	6.16	ns
	-1	0.56	3.34	0.04	1.04	0.36	3.34	3.34	3.06	3.00	5.24	5.24	ns
	-2	0.49	2.93	0.03	0.91	0.32	2.93	2.93	2.69	2.63	4.60	4.60	ns
12 mA	Std.	0.66	3.53	0.04	1.22	0.43	3.60	3.04	3.70	4.08	5.84	5.28	ns
	-1	0.56	3.01	0.04	1.04	0.36	3.06	2.59	3.15	3.47	4.96	4.49	ns
	-2	0.49	2.64	0.03	0.91	0.32	2.69	2.27	2.76	3.05	4.36	3.94	ns
16 mA	Std.	0.66	3.53	0.04	1.22	0.43	3.60	3.04	3.70	4.08	5.84	5.28	ns
	-1	0.56	3.01	0.04	1.04	0.36	3.06	2.59	3.15	3.47	4.96	4.49	ns
	-2	0.49	2.64	0.03	0.91	0.32	2.69	2.27	2.76	3.05	4.36	3.94	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

Table 2-71 • 1.8 V LVC MOS Low Slew

 Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.7 V
 Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.66	15.53	0.04	1.22	0.43	14.11	15.53	2.78	1.60	16.35	17.77	ns
	-1	0.56	13.21	0.04	1.04	0.36	12.01	13.21	2.36	1.36	13.91	15.11	ns
	-2	0.49	11.60	0.03	0.91	0.32	10.54	11.60	2.07	1.19	12.21	13.27	ns
4 mA	Std.	0.66	10.48	0.04	1.22	0.43	10.41	10.48	3.23	2.73	12.65	12.71	ns
	-1	0.56	8.91	0.04	1.04	0.36	8.86	8.91	2.75	2.33	10.76	10.81	ns
	-2	0.49	7.82	0.03	0.91	0.32	7.77	7.82	2.41	2.04	9.44	9.49	ns
6 mA	Std.	0.66	8.05	0.04	1.22	0.43	8.20	7.84	3.54	3.27	10.43	10.08	ns
	-1	0.56	6.85	0.04	1.04	0.36	6.97	6.67	3.01	2.78	8.88	8.57	ns
	-2	0.49	6.01	0.03	0.91	0.32	6.12	5.86	2.64	2.44	7.79	7.53	ns
8 mA	Std.	0.66	7.50	0.04	1.22	0.43	7.64	7.30	3.61	3.41	9.88	9.53	ns
	-1	0.56	6.38	0.04	1.04	0.36	6.50	6.21	3.07	2.90	8.40	8.11	ns
	-2	0.49	5.60	0.03	0.91	0.32	5.71	5.45	2.69	2.55	7.38	7.12	ns
12 mA	Std.	0.66	7.29	0.04	1.22	0.43	7.23	7.29	3.71	3.95	9.47	9.53	ns
	-1	0.56	6.20	0.04	1.04	0.36	6.15	6.20	3.15	3.36	8.06	8.11	ns
	-2	0.49	5.45	0.03	0.91	0.32	5.40	5.45	2.77	2.95	7.07	7.12	ns
16 mA	Std.	0.66	7.29	0.04	1.22	0.43	7.23	7.29	3.71	3.95	9.47	9.53	ns
	-1	0.56	6.20	0.04	1.04	0.36	6.15	6.20	3.15	3.36	8.06	8.11	ns
	-2	0.49	5.45	0.03	0.91	0.32	5.40	5.45	2.77	2.95	7.07	7.12	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

VersaTile Characteristics

VersaTile Specifications as a Combinatorial Module

The ProASIC3 library offers all combinations of LUT-3 combinatorial functions. In this section, timing characteristics are presented for a sample of the library. For more details, refer to the [Fusion, IGLOO®/e, and ProASIC3/E Macro Library Guide](#).

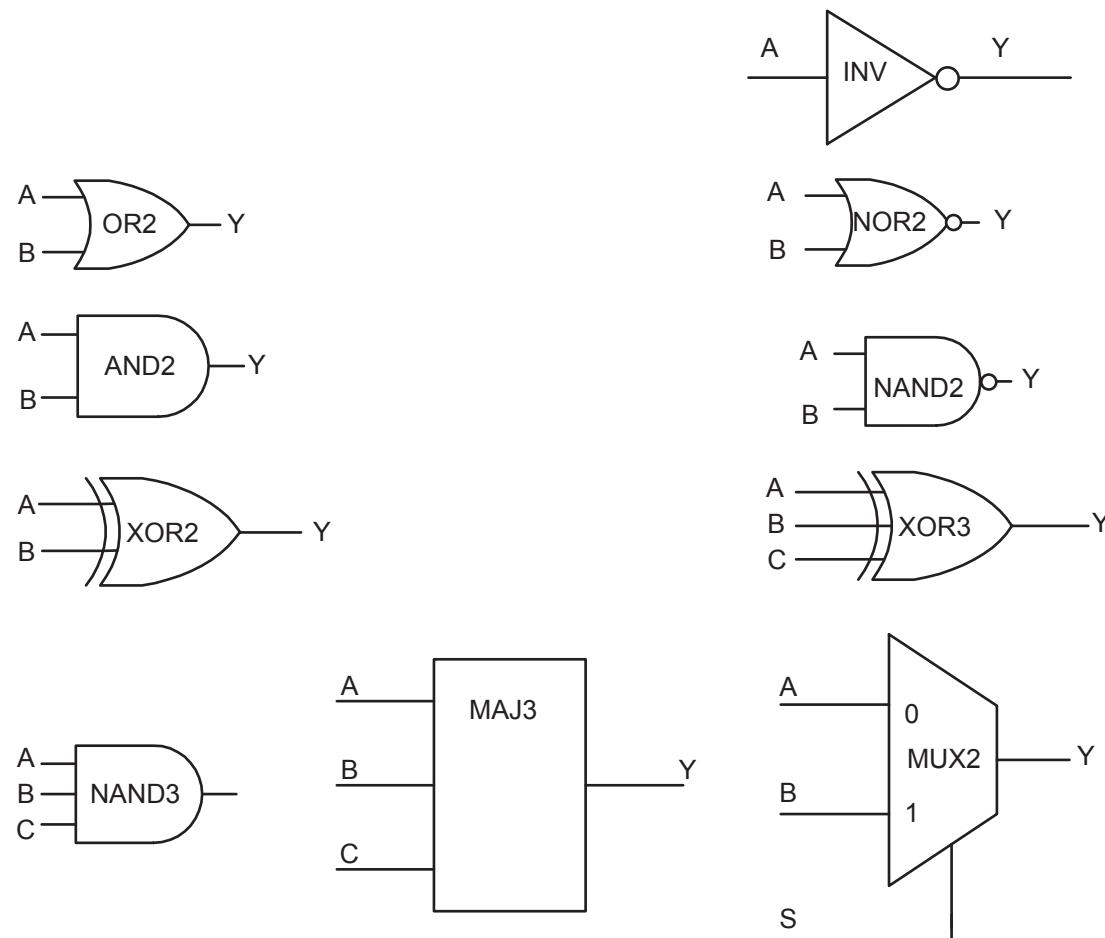


Figure 2-24 • Sample of Combinatorial Cells

Embedded SRAM and FIFO Characteristics

SRAM

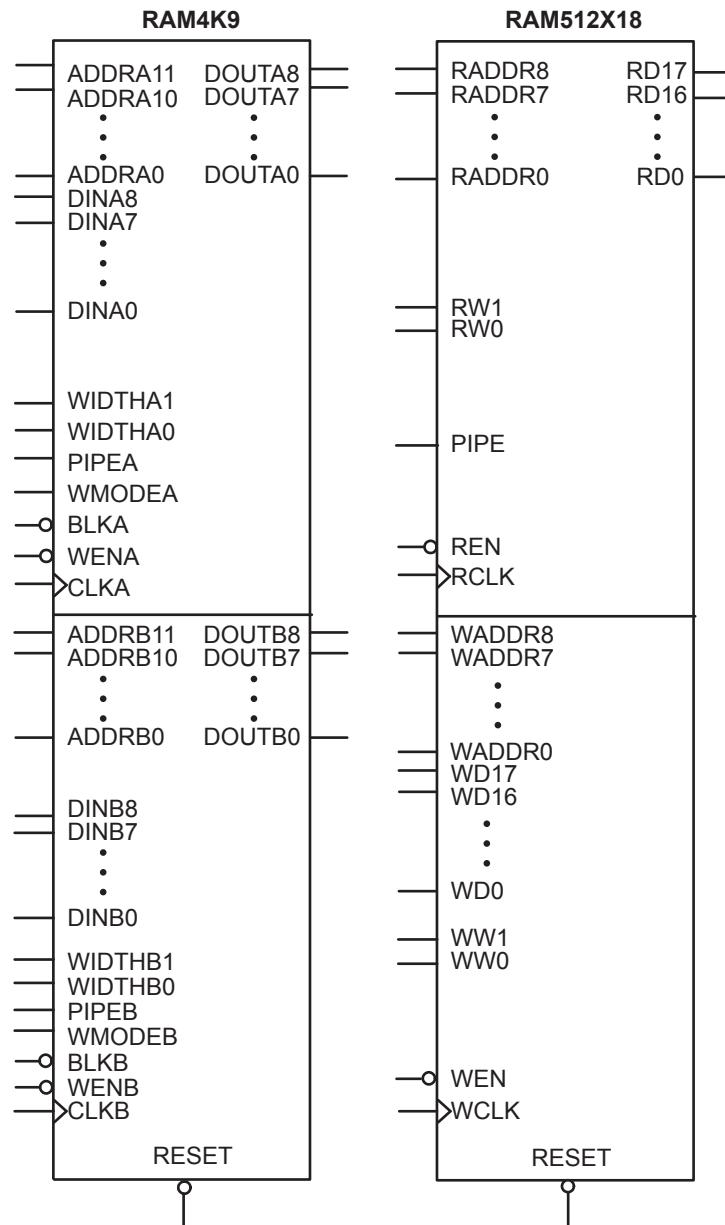


Figure 2-30 • RAM Models

Table 2-122 • A3P250 FIFO 2k×2
Worst Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, VCC = 1.425 V

Parameter	Description	-2	-1	Std.	Units
t_{ENS}	REN, WEN Setup Time	4.39	5.00	5.88	ns
t_{ENH}	REN, WEN Hold Time	0.00	0.00	0.00	ns
t_{BKS}	BLK Setup Time	0.19	0.22	0.26	ns
t_{BKH}	BLK Hold Time	0.00	0.00	0.00	ns
t_{DS}	Input Data (WD) Setup Time	0.18	0.21	0.25	ns
t_{DH}	Input Data (WD) Hold Time	0.00	0.00	0.00	ns
t_{CKQ1}	Clock High to New Data Valid on RD (flow-through)	2.36	2.68	3.15	ns
t_{CKQ2}	Clock High to New Data Valid on RD (pipelined)	0.89	1.02	1.20	ns
t_{RCKEF}	RCLK High to Empty Flag Valid	1.72	1.96	2.30	ns
t_{WCKFF}	WCLK High to Full Flag Valid	1.63	1.86	2.18	ns
t_{CKAF}	Clock High to Almost Empty/Full Flag Valid	6.19	7.05	8.29	ns
t_{RSTFG}	RESET Low to Empty/Full Flag Valid	1.69	1.93	2.27	ns
t_{RSTAF}	RESET Low to Almost Empty/Full Flag Valid	6.13	6.98	8.20	ns
t_{RSTBQ}	RESET Low to Data Out Low on RD (flow-through)	0.92	1.05	1.23	ns
	RESET Low to Data Out Low on RD (pipelined)	0.92	1.05	1.23	ns
$t_{REMRSTB}$	RESET Removal	0.29	0.33	0.38	ns
$t_{RECRSTB}$	RESET Recovery	1.50	1.71	2.01	ns
$t_{MPWRSTB}$	RESET Minimum Pulse Width	0.21	0.24	0.29	ns
t_{CYC}	Clock Cycle Time	3.23	3.68	4.32	ns
F_{MAX}	Maximum Frequency for FIFO	310	272	231	MHz

Table 2-123 • A3P250 FIFO 4k×1
Worst Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, VCC = 1.425 V

Parameter	Description	-2	-1	Std.	Units
t_{ENS}	REN, WEN Setup Time	4.86	5.53	6.50	ns
t_{ENH}	REN, WEN Hold Time	0.00	0.00	0.00	ns
t_{BKS}	BLK Setup Time	0.19	0.22	0.26	ns
t_{BKH}	BLK Hold Time	0.00	0.00	0.00	ns
t_{DS}	Input Data (WD) Setup Time	0.18	0.21	0.25	ns
t_{DH}	Input Data (WD) Hold Time	0.00	0.00	0.00	ns
t_{CKQ1}	Clock High to New Data Valid on RD (flow-through)	2.36	2.68	3.15	ns
t_{CKQ2}	Clock High to New Data Valid on RD (pipelined)	0.89	1.02	1.20	ns
t_{RCKEF}	RCLK High to Empty Flag Valid	1.72	1.96	2.30	ns
t_{WCKFF}	WCLK High to Full Flag Valid	1.63	1.86	2.18	ns
t_{CKAF}	Clock High to Almost Empty/Full Flag Valid	6.19	7.05	8.29	ns
t_{RSTFG}	RESET Low to Empty/Full Flag Valid	1.69	1.93	2.27	ns

QN68	
Pin Number	A3P015 Function
1	IO82RSB1
2	IO80RSB1
3	IO78RSB1
4	IO76RSB1
5	GEC0/IO73RSB1
6	GEA0/IO72RSB1
7	GEB0/IO71RSB1
8	VCC
9	GND
10	VCCIB1
11	IO68RSB1
12	IO67RSB1
13	IO66RSB1
14	IO65RSB1
15	IO64RSB1
16	IO63RSB1
17	IO62RSB1
18	IO60RSB1
19	IO58RSB1
20	IO56RSB1
21	IO54RSB1
22	IO52RSB1
23	IO51RSB1
24	VCC
25	GND
26	VCCIB1
27	IO50RSB1
28	IO48RSB1
29	IO46RSB1
30	IO44RSB1
31	IO42RSB1
32	TCK
33	TDI
34	TMS
35	VPUMP
36	TDO

QN68	
Pin Number	A3P015 Function
37	TRST
38	VJTAG
39	IO40RSB0
40	IO37RSB0
41	GDB0/IO34RSB0
42	GDA0/IO33RSB0
43	GDC0/IO32RSB0
44	VCCIB0
45	GND
46	VCC
47	IO31RSB0
48	IO29RSB0
49	IO28RSB0
50	IO27RSB0
51	IO25RSB0
52	IO24RSB0
53	IO22RSB0
54	IO21RSB0
55	IO19RSB0
56	IO17RSB0
57	IO15RSB0
58	IO14RSB0
59	VCCIB0
60	GND
61	VCC
62	IO12RSB0
63	IO10RSB0
64	IO08RSB0
65	IO06RSB0
66	IO04RSB0
67	IO02RSB0
68	IO00RSB0

QN132	
Pin Number	A3P030 Function
C17	IO51RSB1
C18	NC
C19	TCK
C20	NC
C21	VPUMP
C22	VJTAG
C23	NC
C24	NC
C25	NC
C26	GDB0/IO38RSB0
C27	NC
C28	VCCIB0
C29	IO32RSB0
C30	IO29RSB0
C31	IO28RSB0
C32	IO25RSB0
C33	NC
C34	NC
C35	VCCIB0
C36	IO17RSB0
C37	IO14RSB0
C38	IO11RSB0
C39	IO07RSB0
C40	IO04RSB0
D1	GND
D2	GND
D3	GND
D4	GND

VQ100	
Pin Number	A3P060 Function
1	GND
2	GAA2/IO51RSB1
3	IO52RSB1
4	GAB2/IO53RSB1
5	IO95RSB1
6	GAC2/IO94RSB1
7	IO93RSB1
8	IO92RSB1
9	GND
10	GFB1/IO87RSB1
11	GFB0/IO86RSB1
12	VCOMPLF
13	GFA0/IO85RSB1
14	VCCPLF
15	GFA1/IO84RSB1
16	GFA2/IO83RSB1
17	VCC
18	VCCIB1
19	GEC1/IO77RSB1
20	GEB1/IO75RSB1
21	GEB0/IO74RSB1
22	GEA1/IO73RSB1
23	GEA0/IO72RSB1
24	VMV1
25	GNDQ
26	GEA2/IO71RSB1
27	GEB2/IO70RSB1
28	GEC2/IO69RSB1
29	IO68RSB1
30	IO67RSB1
31	IO66RSB1
32	IO65RSB1
33	IO64RSB1
34	IO63RSB1
35	IO62RSB1
36	IO61RSB1

VQ100	
Pin Number	A3P060 Function
37	VCC
38	GND
39	VCCIB1
40	IO60RSB1
41	IO59RSB1
42	IO58RSB1
43	IO57RSB1
44	GDC2/IO56RSB1
45	GDB2/IO55RSB1
46	GDA2/IO54RSB1
47	TCK
48	TDI
49	TMS
50	VMV1
51	GND
52	VPUMP
53	NC
54	TDO
55	TRST
56	VJTAG
57	GDA1/IO49RSB0
58	GDC0/IO46RSB0
59	GDC1/IO45RSB0
60	GCC2/IO43RSB0
61	GCB2/IO42RSB0
62	GCA0/IO40RSB0
63	GCA1/IO39RSB0
64	GCC0/IO36RSB0
65	GCC1/IO35RSB0
66	VCCIB0
67	GND
68	VCC
69	IO31RSB0
70	GBC2/IO29RSB0
71	GBB2/IO27RSB0
72	IO26RSB0

VQ100	
Pin Number	A3P060 Function
73	GBA2/IO25RSB0
74	VMVO
75	GNDQ
76	GBA1/IO24RSB0
77	GBA0/IO23RSB0
78	GBB1/IO22RSB0
79	GBB0/IO21RSB0
80	GBC1/IO20RSB0
81	GBC0/IO19RSB0
82	IO18RSB0
83	IO17RSB0
84	IO15RSB0
85	IO13RSB0
86	IO11RSB0
87	VCCIB0
88	GND
89	VCC
90	IO10RSB0
91	IO09RSB0
92	IO08RSB0
93	GAC1/IO07RSB0
94	GAC0/IO06RSB0
95	GAB1/IO05RSB0
96	GAB0/IO04RSB0
97	GAA1/IO03RSB0
98	GAA0/IO02RSB0
99	IO01RSB0
100	IO00RSB0

VQ100	
Pin Number	A3P125 Function
1	GND
2	GAA2/IO67RSB1
3	IO68RSB1
4	GAB2/IO69RSB1
5	IO132RSB1
6	GAC2/IO131RSB1
7	IO130RSB1
8	IO129RSB1
9	GND
10	GFB1/IO124RSB1
11	GFB0/IO123RSB1
12	VCOMPLF
13	GFA0/IO122RSB1
14	VCCPLF
15	GFA1/IO121RSB1
16	GFA2/IO120RSB1
17	VCC
18	VCCIB1
19	GEC0/IO111RSB1
20	GEB1/IO110RSB1
21	GEB0/IO109RSB1
22	GEA1/IO108RSB1
23	GEA0/IO107RSB1
24	VMV1
25	GNDQ
26	GEA2/IO106RSB1
27	GEB2/IO105RSB1
28	GEC2/IO104RSB1
29	IO102RSB1
30	IO100RSB1
31	IO99RSB1
32	IO97RSB1
33	IO96RSB1
34	IO95RSB1
35	IO94RSB1
36	IO93RSB1

VQ100	
Pin Number	A3P125 Function
37	VCC
38	GND
39	VCCIB1
40	IO87RSB1
41	IO84RSB1
42	IO81RSB1
43	IO75RSB1
44	GDC2/IO72RSB1
45	GDB2/IO71RSB1
46	GDA2/IO70RSB1
47	TCK
48	TDI
49	TMS
50	VMV1
51	GND
52	VPUMP
53	NC
54	TDO
55	TRST
56	VJTAG
57	GDA1/IO65RSB0
58	GDC0/IO62RSB0
59	GDC1/IO61RSB0
60	GCC2/IO59RSB0
61	GCB2/IO58RSB0
62	GCA0/IO56RSB0
63	GCA1/IO55RSB0
64	GCC0/IO52RSB0
65	GCC1/IO51RSB0
66	VCCIB0
67	GND
68	VCC
69	IO47RSB0
70	GBC2/IO45RSB0
71	GBB2/IO43RSB0
72	IO42RSB0

VQ100	
Pin Number	A3P125 Function
73	GBA2/IO41RSB0
74	VMV0
75	GNDQ
76	GBA1/IO40RSB0
77	GBA0/IO39RSB0
78	GBB1/IO38RSB0
79	GBB0/IO37RSB0
80	GBC1/IO36RSB0
81	GBC0/IO35RSB0
82	IO32RSB0
83	IO28RSB0
84	IO25RSB0
85	IO22RSB0
86	IO19RSB0
87	VCCIB0
88	GND
89	VCC
90	IO15RSB0
91	IO13RSB0
92	IO11RSB0
93	IO09RSB0
94	IO07RSB0
95	GAC1/IO05RSB0
96	GAC0/IO04RSB0
97	GAB1/IO03RSB0
98	GAB0/IO02RSB0
99	GAA1/IO01RSB0
100	GAA0/IO00RSB0

PQ208	
Pin Number	A3P600 Function
1	GND
2	GAA2/IO174PDB3
3	IO174NDB3
4	GAB2/IO173PDB3
5	IO173NDB3
6	GAC2/IO172PDB3
7	IO172NDB3
8	IO171PDB3
9	IO171NDB3
10	IO170PDB3
11	IO170NDB3
12	IO169PDB3
13	IO169NDB3
14	IO168PDB3
15	IO168NDB3
16	VCC
17	GND
18	VCCIB3
19	IO166PDB3
20	IO166NDB3
21	GFC1/IO164PDB3
22	GFC0/IO164NDB3
23	GFB1/IO163PDB3
24	GFB0/IO163NDB3
25	VCOMPLF
26	GFA0/IO162NPB3
27	VCCPLF
28	GFA1/IO162PPB3
29	GND
30	GFA2/IO161PDB3
31	IO161NDB3
32	GFB2/IO160PDB3
33	IO160NDB3
34	GFC2/IO159PDB3
35	IO159NDB3
36	VCC

PQ208	
Pin Number	A3P600 Function
37	IO152PDB3
38	IO152NDB3
39	IO150PSB3
40	VCCIB3
41	GND
42	IO147PDB3
43	IO147NDB3
44	GEC1/IO146PDB3
45	GEC0/IO146NDB3
46	GEB1/IO145PDB3
47	GEB0/IO145NDB3
48	GEA1/IO144PDB3
49	GEA0/IO144NDB3
50	VMV3
51	GNDQ
52	GND
53	VMV2
54	GEA2/IO143RSB2
55	GEB2/IO142RSB2
56	GEC2/IO141RSB2
57	IO140RSB2
58	IO139RSB2
59	IO138RSB2
60	IO137RSB2
61	IO136RSB2
62	VCCIB2
63	IO135RSB2
64	IO133RSB2
65	GND
66	IO131RSB2
67	IO129RSB2
68	IO127RSB2
69	IO125RSB2
70	IO123RSB2
71	VCC
72	VCCIB2

PQ208	
Pin Number	A3P600 Function
73	IO120RSB2
74	IO119RSB2
75	IO118RSB2
76	IO117RSB2
77	IO116RSB2
78	IO115RSB2
79	IO114RSB2
80	IO112RSB2
81	GND
82	IO111RSB2
83	IO110RSB2
84	IO109RSB2
85	IO108RSB2
86	IO107RSB2
87	IO106RSB2
88	VCC
89	VCCIB2
90	IO104RSB2
91	IO102RSB2
92	IO100RSB2
93	IO98RSB2
94	IO96RSB2
95	IO92RSB2
96	GDC2/IO91RSB2
97	GND
98	GDB2/IO90RSB2
99	GDA2/IO89RSB2
100	GNDQ
101	TCK
102	TDI
103	TMS
104	VMV2
105	GND
106	VPUMP
107	GNDQ
108	TDO

FG256	
Pin Number	A3P1000 Function
R5	IO168RSB2
R6	IO163RSB2
R7	IO157RSB2
R8	IO149RSB2
R9	IO143RSB2
R10	IO138RSB2
R11	IO131RSB2
R12	IO125RSB2
R13	GDB2/IO115RSB2
R14	TDI
R15	GNDQ
R16	TDO
T1	GND
T2	IO183RSB2
T3	GEB2/IO186RSB2
T4	IO172RSB2
T5	IO170RSB2
T6	IO164RSB2
T7	IO158RSB2
T8	IO153RSB2
T9	IO142RSB2
T10	IO135RSB2
T11	IO130RSB2
T12	GDC2/IO116RSB2
T13	IO120RSB2
T14	GDA2/IO114RSB2
T15	TMS
T16	GND

FG484	
Pin Number	A3P1000 Function
R17	GDB1/IO112PPB1
R18	GDC1/IO111PDB1
R19	IO107NDB1
R20	VCC
R21	IO104NDB1
R22	IO105PDB1
T1	IO198PDB3
T2	IO198NDB3
T3	NC
T4	IO194PPB3
T5	IO192PPB3
T6	GEC1/IO190PPB3
T7	IO192NPB3
T8	GNDQ
T9	GEA2/IO187RSB2
T10	IO161RSB2
T11	IO155RSB2
T12	IO141RSB2
T13	IO129RSB2
T14	IO124RSB2
T15	GNDQ
T16	IO110PDB1
T17	VJTAG
T18	GDC0/IO111NDB1
T19	GDA1/IO113PDB1
T20	NC
T21	IO108PDB1
T22	IO105NDB1
U1	IO195PDB3
U2	IO195NDB3
U3	IO194NPB3
U4	GEB1/IO189PDB3
U5	GEB0/IO189NDB3
U6	VMV2
U7	IO179RSB2
U8	IO171RSB2

FG484	
Pin Number	A3P1000 Function
U9	IO165RSB2
U10	IO159RSB2
U11	IO151RSB2
U12	IO137RSB2
U13	IO134RSB2
U14	IO128RSB2
U15	VMV1
U16	TCK
U17	VPUMP
U18	TRST
U19	GDA0/IO113NDB1
U20	NC
U21	IO108NDB1
U22	IO109PDB1
V1	NC
V2	NC
V3	GND
V4	GEA1/IO188PDB3
V5	GEA0/IO188NDB3
V6	IO184RSB2
V7	GEC2/IO185RSB2
V8	IO168RSB2
V9	IO163RSB2
V10	IO157RSB2
V11	IO149RSB2
V12	IO143RSB2
V13	IO138RSB2
V14	IO131RSB2
V15	IO125RSB2
V16	GDB2/IO115RSB2
V17	TDI
V18	GNDQ
V19	TDO
V20	GND
V21	NC
V22	IO109NDB1

FG484	
Pin Number	A3P1000 Function
W1	NC
W2	IO191PDB3
W3	NC
W4	GND
W5	IO183RSB2
W6	GEB2/IO186RSB2
W7	IO172RSB2
W8	IO170RSB2
W9	IO164RSB2
W10	IO158RSB2
W11	IO153RSB2
W12	IO142RSB2
W13	IO135RSB2
W14	IO130RSB2
W15	GDC2/IO116RSB2
W16	IO120RSB2
W17	GDA2/IO114RSB2
W18	TMS
W19	GND
W20	NC
W21	NC
W22	NC
Y1	VCCIB3
Y2	IO191NDB3
Y3	NC
Y4	IO182RSB2
Y5	GND
Y6	IO177RSB2
Y7	IO174RSB2
Y8	VCC
Y9	VCC
Y10	IO154RSB2
Y11	IO148RSB2
Y12	IO140RSB2
Y13	NC
Y14	VCC

Revision	Changes	Page
v2.0 (continued)	Table 3-20 • Summary of I/O Timing Characteristics—Software Default Settings (Advanced) and Table 3-21 • Summary of I/O Timing Characteristics—Software Default Settings (Standard Plus) were updated. Table 3-11 • Different Components Contributing to Dynamic Power Consumption in ProASIC3 Devices was updated. Table 3-24 • I/O Output Buffer Maximum Resistances1 (Advanced) and Table 3-25 • I/O Output Buffer Maximum Resistances1 (Standard Plus) were updated. Table 3-17 • Summary of Maximum and Minimum DC Input Levels Applicable to Commercial and Industrial Conditions was updated. Table 3-28 • I/O Short Currents IOSH/IOSL (Advanced) and Table 3-29 • I/O Short Currents IOSH/IOSL (Standard Plus) were updated. The note in Table 3-32 • I/O Input Rise Time, Fall Time, and Related I/O Reliability was updated. Figure 3-33 • Write Access After Write onto Same Address, Figure 3-34 • Read Access After Write onto Same Address, and Figure 3-35 • Write Access After Read onto Same Address are new. Figure 3-43 • Timing Diagram was updated. Ambient was deleted from the "Speed Grade and Temperature Grade Matrix". Notes were added to the package diagrams identifying if they were top or bottom view. The A3P030 "132-Pin QFN" table is new. The A3P060 "132-Pin QFN" table is new. The A3P125 "132-Pin QFN" table is new. The A3P250 "132-Pin QFN" table is new. The A3P030 "100-Pin VQFP" table is new.	3-20 to 3-20 3-9 3-22 to 3-22 3-18 3-24 to 3-26 3-27 3-82 to 3-84 3-96 iv N/A 4-2 4-4 4-6 4-8 4-11
Advance v0.7 (January 2007)	In the "I/Os Per Package" table, the I/O numbers were added for A3P060, A3P125, and A3P250. The A3P030-VQ100 I/O was changed from 79 to 77.	ii
Advance v0.6 (April 2006)	The term flow-through was changed to pass-through. Table 1 was updated to include the QN132. The "I/Os Per Package" table was updated with the QN132. The footnotes were also updated. The A3P400-FG144 I/O count was updated. "Automotive ProASIC3 Ordering Information" was updated with the QN132. "Temperature Grade Offerings" was updated with the QN132. B-LVDS and M-LDVS are new I/O standards added to the datasheet. The term flow-through was changed to pass-through. Figure 2-7 • Efficient Long-Line Resources was updated. The footnotes in Figure 2-15 • Clock Input Sources Including CLKBUF, CLKBUF_LVDS/LVPECL, and CLKINT were updated. The Delay Increments in the Programmable Delay Blocks specification in Figure 2-24 • ProASIC3E CCC Options. The "SRAM and FIFO" section was updated.	N/A ii ii iii iii N/A N/A 2-7 2-16 2-24 2-21